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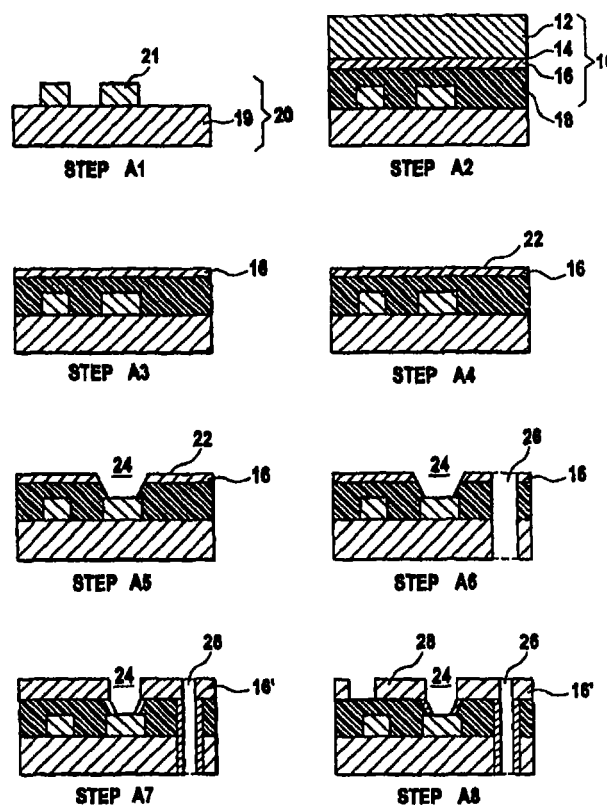


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(54) Title: METHOD FOR MANUFACTURING A MULTILAYER PRINTED CIRCUIT BOARD AND COMPOSITE FOIL FOR USE THEREIN

(57) Abstract

A method for manufacturing a multilayer printed circuit board is disclosed. First a composite foil (10) including a functional copper foil (16) mounted on a carrier foil (12) is laminated on a core board (20). The functional copper foil (16) is less than 10 μm thick, and has a front side facing the carrier foil (12) and a back side coated with a resin (18). Next, the carrier foil (12) is removed from the functional copper foil (16), in order to uncover the front side of the functional copper foil (16). Then, a CO₂ laser source is used to drill holes through the functional copper foil (16) and the resin (18) in order to form microvias (24). It is also disclosed a composite foil (10) comprising four different layers for use in the manufacture of a multilayer printed circuit board.



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